

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of ) **MAIL STOP**  
Akio Katsume et al. )  
Application No.: 09/689,774 ) Group Art Unit: 3726  
Filed: October 13, 2000 ) Examiner: JERMIE E. COZART  
For: HOLDING JIG FOR ELECTRONIC ) Confirmation No.: 8104  
PARTS, HOLDING METHOD )  
THEREFOR, AND )  
MANUFACTURING METHOD FOR )  
ELECTRONIC PARTS )

**REQUEST FOR RECONSIDERATION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated November 19, 2008, reconsideration of the above-identified application is respectfully requested.

Claims 1-4, 7, 9-14 and 19 are pending. Claims 1-4 have been withdrawn.

Claims 7, 9-14 and 19 currently read on the elected species. Claims 7 and 9 were rejected in the November 19, 2008 Office Action. The Office Action summary indicates that claims 9-14 are objected to. However, Applicants are unable to locate a specific objection to these claims in the body of the Office Action. Clarification is respectfully requested.

The Office Action rejects claim 7 under 35 U.S.C. §103(a) over U.S. Patent No. 5,812,570 to Spaeth in view of U.S. Patent No. 3,733,685 to Kauppila; and rejects claim 19 under 35 U.S.C. §103(a) over either Spaeth or Kauppila. It is unclear how the Examiner proposes to reject claim 19 over only Kauppila

considering that claim 19 depends from claim 7 which is rejected over the combination of Spaeth and Kauppila. Clarification is respectfully requested.

The claimed invention relates to a manufacturing method for manufacturing electronic parts such as semiconductor integrated circuits. When electronic parts are manufactured, a holding jig is used to hold the electronic parts in order to handle a plurality of parts collectively.

In related art methods, when a plurality of semiconductor chips are wire bonded by using a holding jig, substrates are arranged in a tray and the semiconductor chips are die bonded to each of the substrates and then wire bonded. Because the substrates are required to be fixed in the tray, an upper surface of the tray was covered by a pressure jig including openings arranged in accordance with an arrangement of the substrates. A pressure leaf spring was used to fix each of the substrates. However, this led to errors in positional recognition during automated processing and required additional processes to correct the errors. Further, the use of pressure leaf springs affected the ability to miniaturize the substrates.

Independent Claim 7 is directed to a method of manufacturing electronic parts, comprising: providing a holding jig made of elastic material, wherein at least one surface of the elastic material is adhesive; mounting a substrate on the holding jig by an adhesive strength of the surface of the elastic material; mounting an element onto said substrate and electrically connecting the element to said substrate while the substrate is held on the surface of the elastic material; and applying ultrasonic waves to a bonding portion at which the electric connection is performed while the substrate is held on the surface of the elastic material.

The Examiner asserts that the connecting material 39 formed of, for example, a soft solder such as Zn or PbZn alloys or a thermally conducting elastic adhesive corresponds to Applicants' claimed holding jig. However, the connecting material 39 is clearly not a holding jig, as described above. Instead, the connecting material 39 is merely used to connect the cooling plate 12 and the connection plate 3 in the device of Spaeth. The Spaeth apparatus involves a laser diode component including a semiconductor body secured on a heat sink. The connecting material 39 is provided between the cooling plate 12, which is part of the heat sink, and the connection plate 3 which is connected to the semiconductor body through the thermally conducting connecting layer 2. Thus, the connecting material 39 is clearly part of the device and not a holding jig. In turn a holding jig is clearly not part of a semiconductor device. Kauppila does not overcome the deficiencies of Spaeth noted above.

The dependent claims are allowable for at least the reasons discussed above as well as for the individual features they recite. Early and favorable action with respect to this application is respectfully requested.

Should any questions arise in connection with this application, or should the Examiner believe that a telephone conference with the undersigned would be helpful in resolving any remaining issues pertaining to this application, the undersigned respectfully requests that he be contacted at the number indicated below.

Respectfully submitted,

BUCHANAN INGERSOLL & ROONEY PC

Date: January 23, 2009

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